

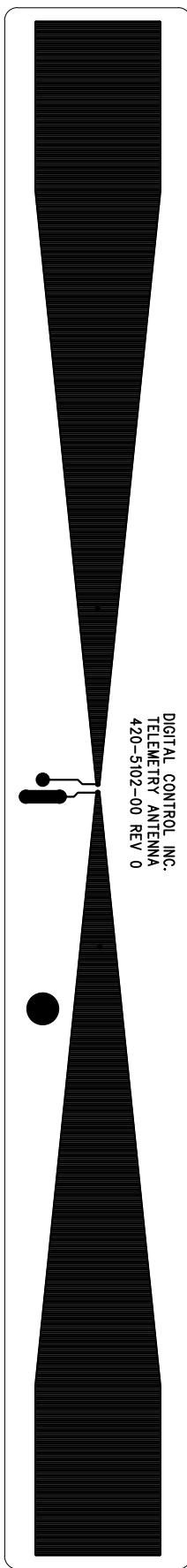
Statement from Digital Control Incorporated:

The DigiRadio™2 module (model DR2), designed for use in DigiTrak® brand handheld receivers (UHF transmitter) and remote displays (UHF receiver), is installed in the host devices at the manufacturer.

The antenna used in the UHF transmitter host devices is also installed at the manufacturer.

The maximum gain of the antenna used with the DR2 module is 0.1 dBi.

The antenna drawing is shown below. Note the antenna type is: dipole.



PCB FABRICATION NOTES (UNLESS OTHERWISE SPECIFIED)

1. PRIMARY SIDE SHOWN.
2. TWO LAYER ROHS COMPLIANT PCB.
3. FABRICATE PER IPC-RB-276 IPC-6012, CLASS 2, CURRENT REV.
4. DETERMINE ACCEPTABILITY PER IPC-A-600, CLASS 2, CURRENT REV.
5. 25% BREAKOUT PERMITTED ON VIAS IF INTERFACE BETWEEN CONDUCTOR AND TERMINAL AREA OF PAD IS 100X.
6. MANUFACTURE AND FABRICATE SHALL BE AS PER IPC-4012/1, USE 0.062" +/-10% THICK.
7. MANUFACTURE/FABRICATE TO MEET THE RoHS DIRECTIVE.
8. GLASS TRANSITION TEMPERATURE (T_g) >70degC
9. DECOMPOSITION TEMPERATURE (T_d) >345degC
10. MOISTURE ABSORPTION RATE $< 0.35\%$
11. BOARD TO BE MEASURED OUTER METAL-TO-METAL THICKNESS.
12. PLATE TO 1.5 OZ COPPER NOMINAL ON SURFACE LAYERS, 1.0 OZ COPPER NOMINAL IN HOLES AND INTERIOR LAYERS IF PRESENT.
13. HOLE PLATING = 0.001"MIN AVERAGE / 0.0008" ABSOLUTE MIN.
14. PLATING HOLE DIAMETERS SPECIFIED AFTER PLATING (SEE: HOLE CHART).
15. MINIMUM COPPER THICKNESS ANYWHERE ON BOARD IS 0.001".
16. TOOLING HOLES OF DIAMETER UP TO 0.126" PERMISSIBLE AND ARE NON-PLATED. IF PRESENT IN DESIGN, THEY SHALL BE MARKED "T". ALL OTHER HOLES SHALL BE PLATED OR NON-PLATED ACCORDING TO HOLE CHART.
17. HOLE SIZES GIVEN ARE FINISHED DIMENSIONS GIVEN IN THOUSANDS OF AN INCH. EXAMPLE: .35 SHALL BE READ AS .035".
18. SOLDERMASK BOTH SIDES OVER BARE COPPER PER IPC-SM-840, CLASS 2, CURRENT REV. AND MANUFACTURERS SPECIFICATIONS.
19. TYPE: LIQUID PHOTOMIGEABLE . COLOR: GREEN.
20. NO BARE COPPER ALLOWED.
21. NO SOLDER MASK PERMISSIBLE ON COMPONENT PADS AS PER SUPPLIED FILMWORK.
22. FINISH: ELECTROLESS NICKEL/IMMERSION GOLD (ENG),
23. EDGE CONNECTOR 14 CONTACT FINGERS TO BE GOLD PLATED.
24. 30 MICRONCHES MINIMUM OF HARD GOLD (99.7%) OVER 200 MICRONCHES OF NICKEL
25. DATE CODE AND UL RECOGNIZED VENDOR MARK REQUIRED.
26. DATE CODE SHALL USE FOUR NUMERALS, GIVING WORK WEEK AND YEAR, EG, 2898 STANDS FOR THE 28TH WEEK OF 1998.
27. THESE MARKS SHALL BE MADE IN COPPER AND SHALL BE LOCATED ON THE SECONDARY SIDE OF THE PCB.
28. SCREEN COMPONENT ID WITH NON-CONDUCTING WHITE INK.
29. COMPONENT ID REGISTRATION TO BE WITHIN +/- 0.005" OF ITS RESPECTIVE COMPONENT LAYER.
30. NO SILKSCREEN INK PERMISSIBLE ON COMPONENT PADS OR IN PADS AS PER SUPPLIED FILMWORK.
31. ETCH TOLERANCE +/-0.001" - +/-0.002" TOTAL TRACE REDUCTION CANNOT EXCEED 20%.
32. FRONT-TO-BACK REGISTRATION TO BE WITHIN +/-0.003".
33. BOARD WARP TO BE NO GREATER THAN 12%.
34. HOLE TOLERANCES
35. UP TO 0.018" DIA +0.000/- 0.003"
36. UP TO 0.020" - 0.049" DIA +/- 0.003"
37. 0.050 0.099" DIA +/- 0.003"
38. 0.100" AND UP +/- 0.007"
39. SOLDER OR PLATING PLUG ACCEPTABLE IN HOLES UP TO 0.025"
40. LAYER CONFIGURATION DIAGRAM:

PRIMARY SIDE COMPONENT ID:
 PRIMARY SIDE SOLDER MASK
 CIRCUIT LAYER #1 (PRIMARY SIDE)
 CIRCUIT LAYER #2 (SECONDARY SIDE)
 SECONDARY SIDE SOLDER MASK
 SECONDARY SIDE SILK SCREEN

DETAIL 1
 SEE VIEW OF PCB (NOT TO SCALE)

0.025mm

180mm

CONFIDENTIAL

DRAWING #:	08-11-08	TITLE:	08-11-08	REVISION:	0
CHECKED:	QC:	SIZE:	DIGITAL DRAWING NO.:	410-502-00	HE:
RELEASED:		SCALE:			

SIZE	QTY	SYN	PLATED	TOL
49	3	<input checked="" type="checkbox"/>	YES	+/-.00
125	1	<input checked="" type="checkbox"/>	YES	+/-.00

